

Electronic Acknowledgement Receipt

EFS ID:	2231951
Application Number:	10632553
International Application Number:	
Confirmation Number:	2573
Title of Invention:	SEMICONDUCTOR MULTI-PACKAGE MODULE HAVING PACKAGE STACKED OVER DIE-DOWN FLIP CHIP BALL GRID ARRAY PACKAGE AND HAVING WIRE BOND INTERCONNECT BETWEEN STACKED PACKAGES
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Attorney Docket Number:	CPAC 1017-6 D4
Receipt Date:	24-SEP-2007
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Application Type:	Utility under 35 USC 111(a)

Payment information:

Submitted with Payment	no
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File Listing:

Document Number	Document Description	File Name	File Size(Bytes) /Message Digest	Multi Part /.zip	Pages (if appl.)
1	Power of Attorney	27-405-5_ChipPAC_Inc_signed_POA.pdf	71697 9a95ec80b32db457ab53ad14cf1d19ac916d86dc	no	1

Warnings:

Information:					
2	Assignee showing of ownership per 37 CFR 3.73(b).	27-405-5_STATEMENT_und er_3-73b.pdf	66883	no	1
			2860b5183dbb642217a5367380f7715a 5fb0e1f4		
Warnings:					
Information:					
3	Change of Address	27-405-5_Fee_Address_Indi cation_Form.pdf	66170	no	1
			52c9351a5c5000fc01b9773455f16ee25 6453f68		
Warnings:					
Information:					
Total Files Size (in bytes):			204750		
<p>This Acknowledgement Receipt evidences receipt on the noted date by the USPTO of the indicated documents, characterized by the applicant, and including page counts, where applicable. It serves as evidence of receipt similar to a Post Card, as described in MPEP 503.</p> <p><u>New Applications Under 35 U.S.C. 111</u> If a new application is being filed and the application includes the necessary components for a filing date (see 37 CFR 1.53(b)-(d) and MPEP 506), a Filing Receipt (37 CFR 1.54) will be issued in due course and the date shown on this Acknowledgement Receipt will establish the filing date of the application.</p> <p><u>National Stage of an International Application under 35 U.S.C. 371</u> If a timely submission to enter the national stage of an international application is compliant with the conditions of 35 U.S.C. 371 and other applicable requirements a Form PCT/DO/EO/903 indicating acceptance of the application as a national stage submission under 35 U.S.C. 371 will be issued in addition to the Filing Receipt, in due course.</p> <p><u>New International Application Filed with the USPTO as a Receiving Office</u> If a new international application is being filed and the international application includes the necessary components for an international filing date (see PCT Article 11 and MPEP 1810), a Notification of the International Application Number and of the International Filing Date (Form PCT/RO/105) will be issued in due course, subject to prescriptions concerning national security, and the date shown on this Acknowledgement Receipt will establish the international filing date of the application.</p>					